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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	17110
Number of Logic Elements/Cells	362000
Total RAM Bits	19822592
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.12V ~ 1.18V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxfb3h4f35i3g

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Symbol	Description	Condition (V)	Overshoot Duration as % of High Time	Unit
		3.8	100	%
		3.85	68	%
		3.9	45	%
		3.95	28	%
		4	15	%
		4.05	13	%
		4.1	11	%
		4.15	9	%
Vi (AC)	AC input voltage	4.2	8	%
		4.25	7	%
		4.3	5.4	%
		4.35	3.2	%
		4.4	1.9	%
		4.45	1.1	%
		4.5	0.6	%
		4.55	0.4	%
		4.6	0.2	%

Recommended Operating Conditions

This section lists the functional operation limits for the AC and DC parameters for Arria V devices.

Recommended Operating Conditions

Table 1-3: Recommended Operating Conditions for Arria V Devices

This table lists the steady-state voltage values expected from Arria V devices. Power supply ramps must all be strictly monotonic, without plateaus.



I/O Standard	V _{CCIO} (V)		V _{SWI}	_{ING(DC)} (V)		V _{X(AC)} (V)		V _{SI}	_{WING(AC)} (V)	
i/O Stalldard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Max
SSTL-125	1.19	1.25	1.31	0.18	(15)	V _{CCIO} /2 - 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} – V _{REF})	$2(V_{IL(AC)} - V_{REF})$

Differential HSTL and HSUL I/O Standards

Table 1-18: Differential HSTL and HSUL I/O Standards for Arria V Devices

I/O Standard		V _{CCIO} (V)		V _{DI}	_{F(DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)		V	_{DIF(AC)} (V)
i/O Stailualu	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	_	0.78	_	1.12	0.78	_	1.12	0.4	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	_	0.68	_	0.9	0.68	_	0.9	0.4	
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	_	$0.5 \times V_{\rm CCIO}$	_	$\begin{array}{c} 0.4 \times \\ V_{\rm CCIO} \end{array}$	$0.5 \times V_{\rm CCIO}$	$0.6 \times V_{\rm CCIO}$	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	$\begin{array}{c} 0.5 \times \\ V_{\rm CCIO} - \\ 0.12 \end{array}$	$0.5 \times V_{\rm CCIO}$	$\begin{array}{c} 0.5 \times \\ V_{\text{CCIO}} \\ + 0.12 \end{array}$	$\begin{array}{c} 0.4 \times \\ V_{\rm CCIO} \end{array}$	$0.5 \times V_{\rm CCIO}$	0.6 × V _{CCIO}	0.44	0.44

Differential I/O Standard Specifications

Table 1-19: Differential I/O Standard Specifications for Arria V Devices

Differential inputs are powered by $\rm V_{\rm CCPD}$ which requires 2.5 V.

Protocol	Sub-protocol	Data Rate (Mbps)
	CPRI E6LV	614.4
	CPRI E6HV	614.4
	CPRI E6LVII	614.4
	CPRI E12LV	1,228.8
	CPRI E12HV	1,228.8
	CPRI E12LVII	1,228.8
Common Public Radio Interface (CPRI)	CPRI E24LV	2,457.6
	CPRI E24LVII	2,457.6
	CPRI E30LV	3,072
	CPRI E30LVII	3,072
	CPRI E48LVII	4,915.2
	CPRI E60LVII	6,144
	CPRI E96LVIII(60)	9,830.4
Gbps Ethernet (GbE)	GbE 1250	1,250
	OBSAI 768	768
OBSAI	OBSAI 1536	1,536
OBSAI	OBSAI 3072	3,072
	OBSAI 6144	6,144
	SDI 270 SD	270
Serial digital interface (SDI)	SDI 1485 HD	1,485
	SDI 2970 3G	2,970



⁽⁶⁰⁾ You can achieve compliance with TX channel restriction of one HSSI channel per six-channel transceiver bank.

DSP Block Performance Specifications

Table 1-37: DSP Block Performance Specifications for Arria V Devices

	Mode			Performance			
				- C 6	Unit		
	Independent 9 × 9 multiplication	370	310	220	MHz		
	Independent 18 × 19 multiplication	370	310	220	MHz		
	Independent 18 × 25 multiplication	370	310	220	MHz		
C	Independent 20 × 24 multiplication	370	310	220	MHz		
Block	Independent 27 × 27 multiplication	310	250	200	MHz		
	Two 18 × 19 multiplier adder mode	370	310	220	MHz		
	18×18 multiplier added summed with 36-bit input	370	310	220	MHz		
Modes using Two DSP Blocks	Complex 18 × 19 multiplication	370	310	220	MHz		

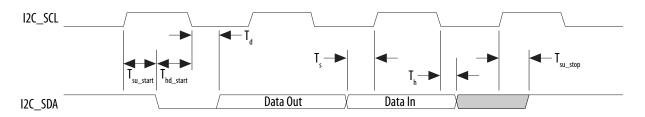
Memory Block Performance Specifications

To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL and set to 50% output duty cycle. Use the Quartus Prime software to report timing for the memory block clocking schemes.

When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in f_{MAX} .



Figure 1-16: I²C Timing Diagram



NAND Timing Characteristics

Table 1-60: NAND ONFI 1.0 Timing Requirements for Arria V Devices

The NAND controller supports Open NAND FLASH Interface (ONFI) 1.0 Mode 5 timing as well as legacy NAND devices. This table lists the requirements for ONFI 1.0 mode 5 timing. The HPS NAND controller can meet this timing by programming the C4 output of the main HPS PLL and timing registers provided in the NAND controller.

Symbol	Description	Min	Max	Unit
$T_{wp}^{(89)}$	Write enable pulse width	10	_	ns
T _{wh} ⁽⁸⁹⁾	Write enable hold time	7	_	ns
T _{rp} ⁽⁸⁹⁾	Read enable pulse width	10		ns
$T_{reh}^{(89)}$	Read enable hold time	7	_	ns
$T_{clesu}^{(89)}$	Command latch enable to write enable setup time	10	_	ns
T _{cleh} ⁽⁸⁹⁾	Command latch enable to write enable hold time	5	_	ns
T _{cesu} ⁽⁸⁹⁾	Chip enable to write enable setup time	15	_	ns
$T_{ceh}^{(89)}$	Chip enable to write enable hold time		_	ns
T _{alesu} (89)	Address latch enable to write enable setup time	10	_	ns
T _{aleh} ⁽⁸⁹⁾	Address latch enable to write enable hold time	5	_	ns
$T_{dsu}^{(89)}$	Data to write enable setup time	10	_	ns

⁽⁸⁹⁾ Timing of the NAND interface is controlled through the NAND configuration registers.

Arria V GX, GT, SX, and ST Device Datasheet



FPP Configuration Timing

DCLK-to-DATA[] Ratio (r) for FPP Configuration

Fast passive parallel (FPP) configuration requires a different DCLK-to-DATA[] ratio when you turn on encryption or the compression feature.

Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the DATA[] rate in byte per second (Bps) or word per second (Wps). For example, in FPP ×16 where the r is 2, the DCLK frequency must be 2 times the DATA[] rate in Wps.

Table 1-65: DCLK-to-DATA[] Ratio for Arria V Devices

Configuration Scheme	Encryption	Compression	DCLK-to-DATA[] Ratio (r)
	Off	Off	1
FPP (8-bit wide)	On	Off	1
TTT (0-bit wide)	Off	On	2
	On	On	2
	Off	Off	1
FPP (16-bit wide)	On	Off	2
TTT (10-bit wide)	Off	On	4
	On	On	4

FPP Configuration Timing when DCLK-to-DATA[] = 1

When you enable decompression or the design security feature, the DCLK-to-DATA[] ratio varies for FPP $\times 8$ and FPP $\times 16$. For the respective DCLK-to-DATA[] ratio, refer to the DCLK-to-DATA[] Ratio for Arria V Devices table.

Table 1-66: FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nconfig low to conf_done low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t_{CFG}	nconfig low pulse width	2	_	μs

Arria V GX, GT, SX, and ST Device Datasheet

Altera Corporation



Term	Definition			
	Transmitter Output Waveforms			
	Single-Ended Waveform Positive Channel (p) = V _{OH} Negative Channel (n) = V _{OL} Ground			
	Differential Waveform			
f_{HSCLK}	Left/right PLL input clock frequency.			
f_{HSDR}	High-speed I/O block—Maximum/minimum LVDS data transfer rate (f _{HSDR} =1/TUI), non-DPA.			
f _{HSDRDPA}	High-speed I/O block—Maximum/minimum LVDS data transfer rate (f _{HSDRDPA} =1/TUI), DPA.			
J	High-speed I/O block—Deserialization factor (width of parallel data bus).			

Term	Definition
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—Clock boost factor

Document Revision History

Date	Version	Changes
December 2016	2016.12.09	 Updated V_{ICM} (AC coupled) specifications in Receiver Specifications for Arria V GX and SX Devices table. Added maximum specification for T_d in Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices table. Updated T_{init} specifications in the following tables: FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Arria V Devices FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Arria V Devices AS Timing Parameters for AS ×1 and ×4 Configurations in Arria V Devices PS Timing Parameters for Arria V Devices
June 2016	2016.06.10	 Changed pin capacitance to maximum values. Updated SPI Master Timing Requirements for Arria V Devices table. Added T_{su} and T_h specifications. Removed T_{dinmax} specifications. Updated SPI Master Timing Diagram. Updated T_{clk} spec from maximum to minimum in I²C Timing Requirements for Arria V Devices table.



Date	Version	Changes
November 2012	3.0	 Updated Table 2, Table 4, Table 9, Table 14, Table 16, Table 17, Table 20, Table 21, Table 25, Table 29, Table 36, Table 56, Table 57, and Table 60. Removed table: Transceiver Block Jitter Specifications for Arria V Devices. Added HPS information: Added "HPS Specifications" section. Added Table 38, Table 39, Table 40, Table 41, Table 42, Table 43, Table 44, Table 45, Table 46, Table 47, Table 48, Table 49, and Table 50. Added Figure 7, Figure 8, Figure 9, Figure 10, Figure 11, Figure 12, Figure 13, Figure 14, Figure 15, Figure 16, Figure 17, Figure 18, and Figure 19. Updated Table 3 and Table 5.
October 2012	2.4	 Updated Arria V GX V_{CCR_GXBL/R}, V_{CCT_GXBL/R}, and V_{CCL_GXBL/R} minimum and maximum values, and data rate in Table 4. Added receiver V_{ICM} (AC coupled) and V_{ICM} (DC coupled) values, and transmitter V_{OCM} (AC coupled) and V_{OCM} (DC coupled) values in Table 20 and Table 21.
August 2012	2.3	Updated the SERDES factor condition in Table 30.
July 2012	2.2	 Updated the maximum voltage for V_I (DC input voltage) in Table 1. Updated Table 20 to include the Arria V GX -I3 speed grade. Updated the minimum value of the fixedclk clock frequency in Table 20 and Table 21. Updated the SERDES factor condition in Table 30. Updated Table 50 to include the IOE programmable delay settings for the Arria V GX -I3 speed grade.
June 2012	2.1	Updated $V_{CCR_GXBL/R}$, $V_{CCT_GXBL/R}$, and $V_{CCL_GXBL/R}$ values in Table 4.



I/O Standard	V _{CCIO} (V)		V _{DIF}	_(DC) (V)		$V_{X(AC)}(V)$		V _{CN}	_{M(DC)} (V)	V	_{DIF(AC)} (V)	
i/O Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	_	$0.5 \times V_{CCIO}$	_	$0.4 \times V_{\rm CCIO}$	0.5 × V _{CC} IO	$0.6 \times V_{\text{CCIO}}$	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5 × V _{CCIO} – 0.12	$0.5 \times V_{CCIO}$	$0.5 \times V_{\rm CCIO} \\ + 0.12$	$0.4 \times V_{\rm CCIO}$	0.5 × V _{CC}	0.6 × V _{CCIO}	0.44	0.44

Table 2-21: Differential I/O Standard Specifications for Arria V GZ Devices

I/O Standard	V _{CCIO} (V) ⁽¹²⁸⁾			V _{ID} (mV) ⁽¹²⁹⁾			V _{ICM(DC)} (V)		Vo	_D (V) ⁽¹³	0)	V	_{OCM} (V) ⁽¹³	30)	
i/O Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	PCML Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to the "Transceiver Performance Specifications" section.														
2.5 V LVDS	2.375	2.5	2.625	100	V _{CM} =		0.05	$D_{MAX} \le 700 \text{ Mbps}$	1.8	0.247	_	0.6	1.125	1.25	1.375
(131)	LVD3 2.3/3 2.3 2.023 100	1.25 V	_	1.05	D _{MAX} > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375			
BLVDS (132)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	_	_	_	_

 $^{^{\}left(128\right)}\,$ Differential inputs are powered by VCCPD which requires 2.5 V.



⁽¹²⁹⁾ The minimum VID value is applicable over the entire common mode range, VCM.

⁽¹³⁰⁾ RL range: $90 \le RL \le 110 \Omega$.

⁽¹³¹⁾ For optimized LVDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.

⁽¹³²⁾ There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. They depend on the system topology.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transo	eiver Spe	ed Grade 3	Unit
3yiiiboi/Description	Conditions	Min	Тур	Max	Min	Тур	Max	Oille
$\label{eq:maximum peak-to-peak differential} \\ input voltage V_{ID} (diff p-p) before \\ device configuration$	_	_	_	1.6	_	_	1.6	V
Maximum peak-to-peak differential	$V_{\text{CCR_GXB}} = 1.0 \text{ V}$ $(V_{\text{ICM}} = 0.75 \text{ V})$	_	_	1.8	_	_	1.8	V
input voltage V_{ID} (diff p-p) after device configuration $^{(146)}$	$V_{\text{CCR_GXB}} = 0.85 \text{ V}$ $(V_{\text{ICM}} = 0.6 \text{ V})$	_	_	2.4	_	_	2.4	V
Minimum differential eye opening at receiver serial input pins (147)(148)	_	85	_	_	85	_	_	mV
	85– Ω setting		85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination	100–Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
resistors	120–Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150– Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	Ω



 $^{^{(146)} \ \} The\ maximum\ peak\ to\ peak\ differential\ input\ voltage\ V_{ID}\ after\ device\ configuration\ is\ equal\ to\ 4\times (absolute\ V_{MAX}\ for\ receiver\ pin\ -\ V_{ICM}).$

⁽¹⁴⁷⁾ The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

⁽¹⁴⁸⁾ Minimum eye opening of 85 mV is only for the unstressed input eye condition.

Symbol/Description	Conditions	Trans	ceiver Spee	d Grade 2	Transo	eiver Spee	ed Grade 3	Unit
symbol/Description	Conditions	Min	Тур	Max	Min	Тур	Max	Onit
	85- Ω setting	_	85 ± 20%	_	_	85 ± 20%	_	Ω
Differential on-chip termination	100- Ω setting	_	100 ± 20%	_	_	100 ± 20%	_	Ω
resistors	120-Ω setting	_	120 ± 20%	_	_	120 ± 20%	_	Ω
	150- Ω setting	_	150 ± 20%	_	_	150 ± 20%	_	Ω
V _{OCM} (AC coupled)	0.65-V setting	_	650	_	_	650	_	mV
V _{OCM} (DC coupled)	_	_	650	_	_	650	_	mV
Intra-differential pair skew	$Tx V_{CM} = 0.5 V$ and slew rate of 15 ps	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to-channel skew	x6 PMA bonded mode	_	_	120	_	_	120	ps
Inter-transceiver block transmitter channel-to-channel skew	xN PMA bonded mode	_	_	500	_	_	500	ps

Related Information

Arria V Device Overview

For more information about device ordering codes.

Altera Corporation Arria V GZ Device Datasheet



Symbol	Conditions		C3, I3L			Unit		
Зупівої	Containions	Min	Тур	Max	Min	Тур	Max	Offic
f _{HSCLK_in} (input clock frequency) True Differential I/O Standards ⁽¹⁷⁹⁾	Clock boost factor W = 1 to 40 (180)	5	_	625	5	_	525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 (180)	5	_	625	5	_	525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 (180)	5	_	420	5	_	420	MHz
f _{HSCLK_OUT} (output clock frequency)	_	5	_	625 (181)	5	_	525 (181)	MHz

Transmitter High-Speed I/O Specifications

Table 2-40: Transmitter High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.



 $^{^{\}left(179\right)}\,$ This only applies to DPA and soft-CDR modes.

⁽¹⁸⁰⁾ Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.

⁽¹⁸¹⁾ This is achieved by using the LVDS clock network.

Symbol	Conditions		C3, I3L			C4, I4		Unit
Syllibol	Conditions	Min	Тур	Max	Min	Тур	Max	Offic
t _{x Jitter} - True Differential I/O	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	ps
Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_		0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards with Three	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	325	ps
External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_		0.25	UI
$t_{ m DUTY}$	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	200	_	_	200	ps
$t_{RISE} \& t_{FALL}$	Emulated Differential I/O Standards with three external output resistor networks	_	_	250	_	_	300	ps
	True Differential I/O Standards	_	_	150	_	_	150	ps
TCCS	Emulated Differential I/O Standards	_	_	300	_	_	300	ps

Receiver High-Speed I/O Specifications

Table 2-41: Receiver High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.



Figure 2-4: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate ≥ 1.25 Gbps



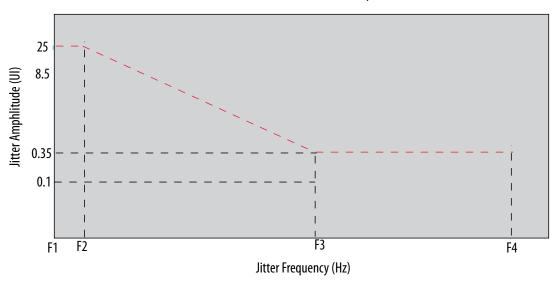


Table 2-45: LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate ≥ 1.25 Gbps

Jitter Free	quency (Hz)	Sinusoidal Jitter (UI)		
F1	F1 10,000			
F2	F2 17,565			
F3	1,493,000	0.350		
F4	50,000,000	0.350		



DLL Range Specifications

Table 2-47: DLL Range Specifications for Arria V GZ Devices

Arria V GZ devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Parameter	C3, I3L	C4, I4	Unit
DLL operating frequency range	300 – 890	300 – 890	MHz

DQS Logic Block Specifications

Table 2-48: DQS Phase Offset Delay Per Setting for Arria V GZ Devices

The typical value equals the average of the minimum and maximum values.

The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -3 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is $[625 \text{ ps} + (10 \times 11 \text{ ps}) \pm 20 \text{ ps}] = 735 \text{ ps} \pm 20 \text{ ps}$.

Speed Grade	Min	Max	Unit
C3, I3L	8	15	ps
C4, I4	8	16	ps

Table 2-49: DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Arria V GZ Devices

This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a -3 speed grade is ± 84 ps or ± 42 ps.

Number of DQS Delay Buffers	C3, I3L	C4, I4	Unit
1	30	32	ps
2	60	64	ps
3	90	96	ps

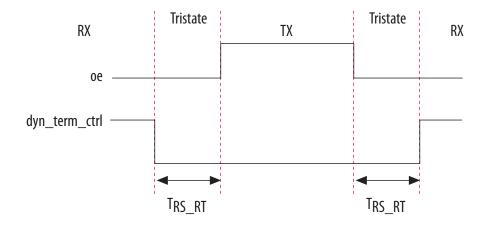


OCT Calibration Block Specifications

Table 2-51: OCT Calibration Block Specifications for Arria V GZ Devices

Symbol	Description	Min	Тур	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks	_	_	20	MHz
T _{OCTCAL}	Number of OCTUSRCLK clock cycles required for OCT R _S /R _T calibration	_	1000	_	Cycles
T _{OCTSHIFT}	Number of OCTUSRCLK clock cycles required for the OCT code to shift out	_	32	_	Cycles
T _{RS_RT}	Time required between the $\tt dyn_term_ctrl$ and $\tt oe$ signal transitions in a bidirectional I/O buffer to dynamically switch between OCT R_S and R_T (See the figure below.)	_	2.5	_	ns

Figure 2-6: Timing Diagram for oe and dyn_term_ctrl Signals





Symbol	Parameter	Minimum	Maximum	Unit
$t_{\rm CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum	_	_
		DCLK period		
t _{CD2UM}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period)	_	_

Related Information

- DCLK-to-DATA[] Ratio (r) for FPP Configuration on page 2-57
- Configuration, Design Security, and Remote System Upgrades in Arria V Devices



⁽²⁰⁸⁾ The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section of the *Configuration*, *Design Security, and Remote System Upgrades in Arria V Devices* chapter.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CO}	DCLK falling edge to AS_DATA0/ASDO output	_	4	ns
t _{SU}	Data setup time before falling edge on DCLK	1.5	_	ns
$t_{\rm H}$	Data hold time after falling edge on DCLK	0	_	ns
t_{CD2UM}	CONF_DONE high to user mode (216)	175	437	μs
$t_{\rm CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period)	_	_

Table 2-59: DCLK Frequency Specification in the AS Configuration Scheme

This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.

The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

Related Information

- Passive Serial Configuration Timing on page 2-67
- Configuration, Design Security, and Remote System Upgrades in Arria V Devices

Altera Corporation

Arria V GZ Device Datasheet

⁽²¹⁶⁾ To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the "Initialization" section of the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

